



## Material Content Data Sheet



Sales Product Name	BF 2030W H6814			Issued		29. August 2013		
MA#	MA000843310							
Package	PG-SOT343-4-1			Weight*		6.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.004	0.05		528	
	non noble metal	tin	7440-31-5	0.001	0.01		136	
	inorganic material	silicon	7440-21-3	0.031	0.46	0.52	4607	5271
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		499	
	non noble metal	chromium	7440-47-3	0.010	0.15		1497	
	non noble metal	copper	7440-50-8	3.347	49.69	49.90	496895	498991
wire	non noble metal	copper	7440-50-8	0.010	0.14	0.14	1440	1440
encapsulation	organic material	carbon black	1333-86-4	0.031	0.46		4552	
	plastics	epoxy resin	-	0.659	9.79		97877	
	inorganic material	silicondioxide	60676-86-0	2.377	35.28	45.53	352811	455240
leadfinish	non noble metal	tin	7440-31-5	0.199	2.96	2.96	29576	29576
plating	noble metal	silver	7440-22-4	0.064	0.95	0.95	9482	9482
*deviation	< 10%	Sum in total:			100,00		1000000	

### Important Remarks:

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